



<b>Session Title:</b>	<b>[TuA1] Advanced Ceria Abrasive Based CMP</b>
<b>Session Date:</b>	<b>November 12 (Tue.), 2024</b>
<b>Session Time:</b>	<b>13:00-14:35</b>
<b>Session Room:</b>	<b>Room A (Capri Room, 2F, Paradise Hotel Busan)</b>
<b>Session Chair:</b>	<b>Prof. Jihoon Seo (Clarkson Univ., USA)</b>

[TuA1-1] [Invited]

13:00-13:25

Effect of Ceria Surface Orientation on SiO<sub>2</sub> CMP

Satoyuki Nomura (Resonac Corp., Japan)

[TuA1-2] [Invited]

13:25-13:50

Development of Spherical Wet Ceria Slurry for Improved Chemical and Mechanical Planarization Performances

Deoksu Han (SK Enpulse Co., Ltd., Korea) and Keon-Soo Jang (The Univ. of Suwon, Korea)

[TuA1-3] [Invited]

13:50-14:15

Colloidal Ceria Innovation and Its Behaviors in Accordance with Abrasive Size

Jae-Dong Lee (KCTech, Korea)

[TuA1-4]

14:15-14:35

Dependency of Amine Surfactant on Diameter and Morphology of Colloidal Silica Abrasives

Min-Uk Jeon, Pil-Su Kim, Ju-Yeon Kim, Eun-Ha Park, Se-Hui Lee, Hye-Min Lee (Hanyang Univ., Korea), Jin-Hyung Park (ENF Tech. Inc., Korea), Jin Sub Park, and Jea-Gun Park (Hanyang Univ., Korea)